

WHAT IS CLAIMED IS:

- 1) An improved process for manufacture and assembly of a plurality of adjoining printed wiring boards, comprising:
 - (a) forming at least a first circuit pattern and a second circuit pattern on a common substrate;
 - (b) connecting at least the first circuit pattern to the second circuit pattern; and
 - (c) separating the common substrate into at least a first substrate and a second substrate with the first substrate including the first circuit pattern thereon and the second substrate including the second circuit pattern thereon.
- 2) The process of **claim 1**, further comprising the step of scoring the common substrate along a dividing line.
- 3) The process of **claim 1**, further comprising the step holding the separated substrates in fixed position relative to each other by a holding fixture.
- 4) The process of **claim 1**, further comprising the step of testing the connection between the first and second circuit patterns prior to the step of separating the common substrate into separate substrates.
- 5) The process of **claim 1**, wherein the step of separating occurs after the step of connecting.
- 6) The process of **claim 3**, wherein the step of connecting occurs after the step of separating.

- 7) The process of **claim 1**, wherein:
 - (a) the common substrate comprises at least a first substrate section and a second substrate section;
 - (b) the step of forming comprises forming a plurality of circuit patterns on the first substrate section and a plurality of circuit patterns on the second substrate section; and
 - (c) the step of connecting further comprises making a plurality of connections between circuit patterns on the first substrate section and the second substrate section.
- 8) The process of **claim 1**, wherein the step of separating further comprises pressing the common substrate along a dividing line until it separates into at least the first and second substrates.
- 9) The process of **claim 1**, wherein the step of separating further comprises cutting the common substrate into a plurality of separate substrates.
- 10) The process of **claim 1**, wherein the step of connecting further comprises attaching at least one electrically conductive wire.
- 11) The process of **claim 10**, wherein the at least one electrically conductive wire comprises a pre-insulated wire.
- 12) The process of **claim 1**, wherein the step of connecting further comprises attaching flexible ribbon wires.
- 13) The process of **claim 1**, wherein the step of connecting further comprises using at least one electrically conductive plastic connection.

